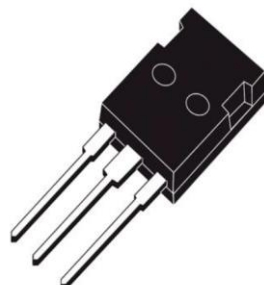


## IGBT

### Features

- 1200V,50A
- $V_{CE(sat)}(typ.)=1.55V@V_{GE}=15V, I_C=50A$
- Positive temperature coefficient
- Fast Switching
- Reliable and Rugged
- Halogen Free and Green Devices Available



TO-247-3L Plus

### General Description

JIAEN Trench IGBTs offer lower losses and higher energy efficiency for application such as UPS, Motor drives, PFC, Portable power station and other soft switching applications.

### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$V_{CES}$	Collector-Emitter Voltage	1200	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 30$	V
$I_C$	Continuous Collector Current ( $T_C=25^{\circ}C$ )	100	A
	Continuous Collector Current ( $T_C=100^{\circ}C$ )	50	A
$I_{CM}$	Pulsed Collector Current (Note 1)	200	A
$I_F$	Diode Continuous Forward Current ( $T_C=100^{\circ}C$ )	50	A
$I_{FM}$	Diode Maximum Forward Current (Note 1)	100	A
$t_{sc}$	Short Circuit Withstand Time	8	us
$P_D$	Maximum Power Dissipation ( $T_C=25^{\circ}C$ )	833	W
$T_J$	Operating Junction Temperature Range	-55 to +175	$^{\circ}C$

### Thermal Characteristics

Symbol	Parameter	Max.	Units
$R_{th\ j-c}$	Thermal Resistance, Junction to case for IGBT	0.18	$^{\circ}C/W$
$R_{th\ j-c}$	Thermal Resistance, Junction to case for Diode	0.37	$^{\circ}C/W$
$R_{th\ j-a}$	Thermal Resistance, Junction to Ambient	40	$^{\circ}C/W$

## Electrical Characteristics ( $T_C=25^{\circ}\text{C}$ unless otherwise noted )

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{CES}$	Collector-Emitter Breakdown Voltage	$V_{GE}=0V, I_C=1mA$	1200	-	-	V
$I_{CES}$	Collector-Emitter Leakage Current	$V_{CE}=1200V, V_{GE}=0V$	-	-	10	$\mu A$
$I_{GES}$	Gate Leakage Current, Forward	$V_{GE}=\pm 20V, V_{CE}=0V$	-	-	$\pm 200$	nA
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE}=V_{CE}, I_C=250\mu A$	4.93	-	6.93	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15V, I_C=50A$	-	1.55	-	V
$Q_g$	Total Gate Charge	$V_{CC}=960V$ $V_{GE}=15V$ $I_C=50A$	-	291	-	nC
$Q_{ge}$	Gate-Emitter Charge		-	81	-	nC
$Q_{gc}$	Gate-Collector Charge		-	110	-	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600V$ $V_{GE}=15V$ $I_C=50A$ $R_G=5\Omega$ Inductive Load $T_C=25^{\circ}\text{C}$	-	44	-	ns
$t_r$	Turn-on Rise Time		-	95	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	190	-	ns
$t_f$	Turn-off Fall Time		-	264	-	ns
$E_{on}$	Turn-on Switching Loss		-	2.57	-	mJ
$E_{off}$	Turn-off Switching Loss		-	3.73	-	mJ
$E_{ts}$	Total Switching Loss		-	6.31	-	mJ
$C_{ies}$	Input Capacitance	$V_{CE}=25V$	-	8408	-	pF
$C_{oes}$	Output Capacitance	$V_{GE}=0V$	-	197	-	pF
$C_{res}$	Reverse Transfer Capacitance	$f=1MHz$	-	55	-	pF

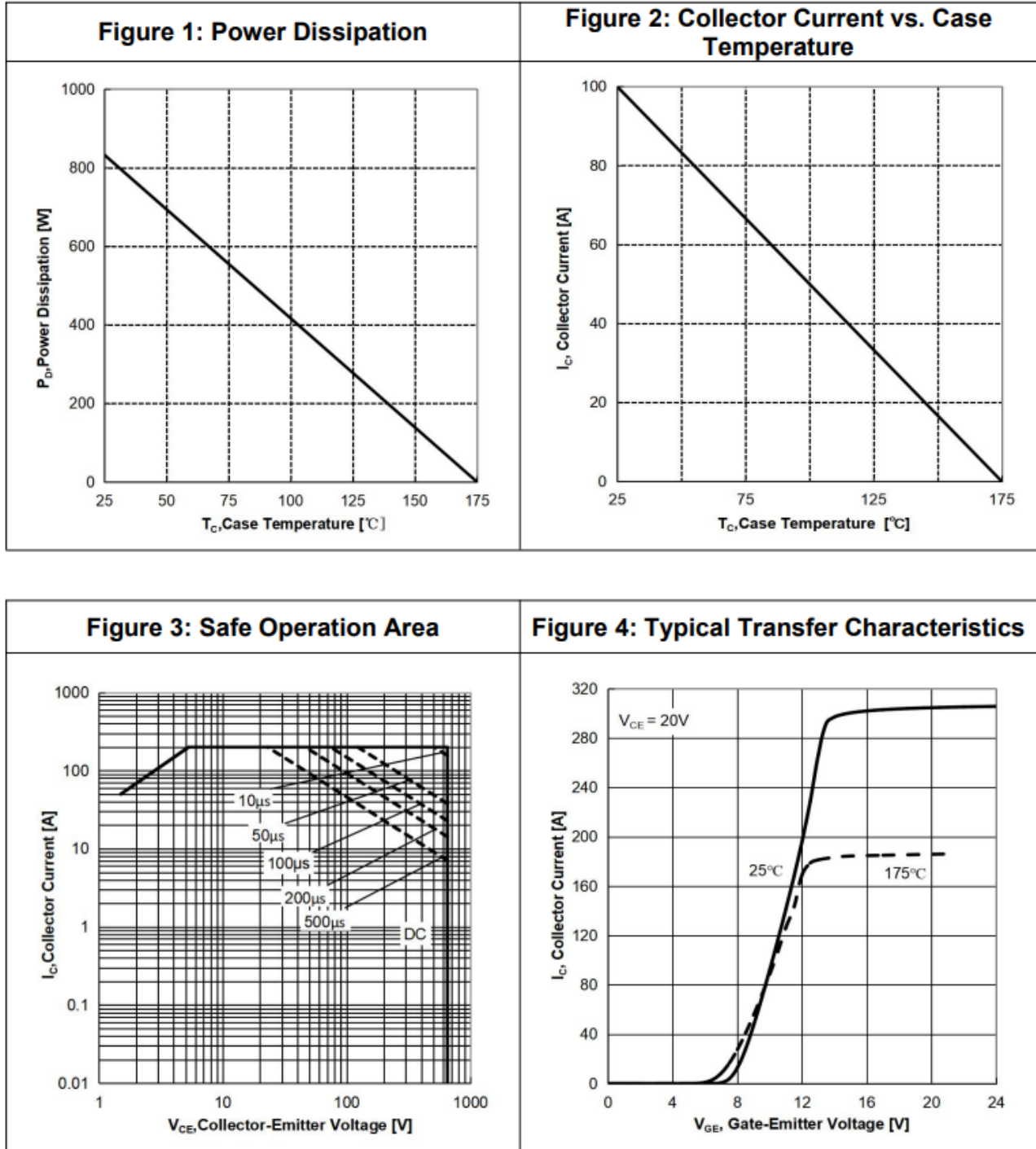
## Electrical Characteristics of Diode ( $T_C=25^{\circ}\text{C}$ unless otherwise noted )

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_F$	Diode Forward Voltage	$I_F=50A$	-	2.0	3.5	V
$t_{rr}$	Diode Reverse Recovery Time	$V_{CE}=600V$ $I_F=50A$ $di_F/dt=200A/\mu s$	-	94	-	ns
$I_{rr}$	Diode peak Reverse Recovery Current		-	9.7	-	A
$Q_{rr}$	Diode Reverse Recovery Charge		-	225	-	nC

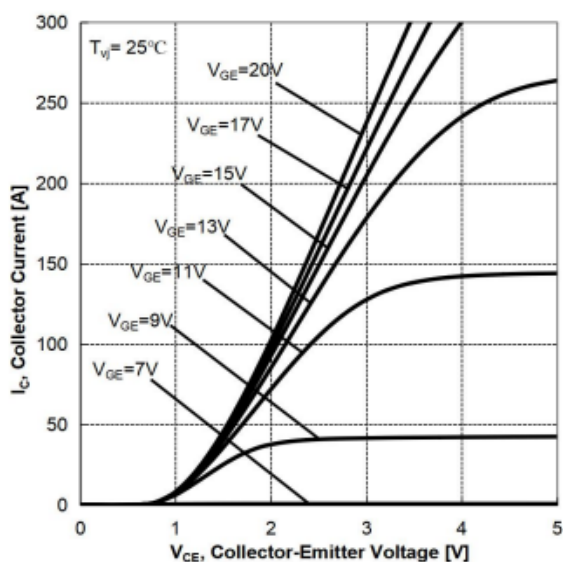
### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature

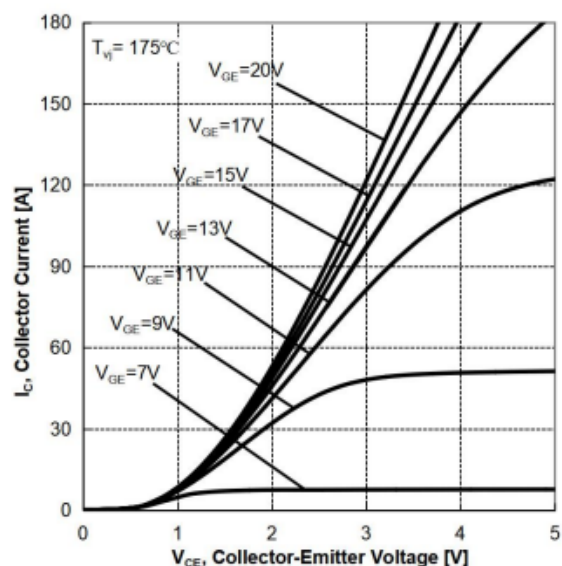
## Typical Performance Characteristics



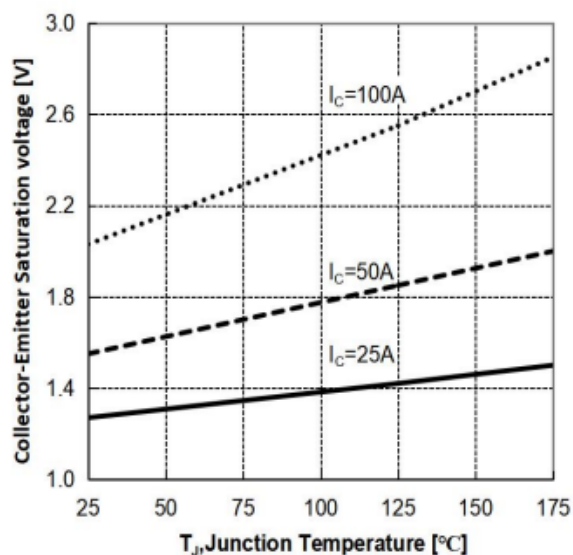
**Figure 5: Typical Output Characteristics**



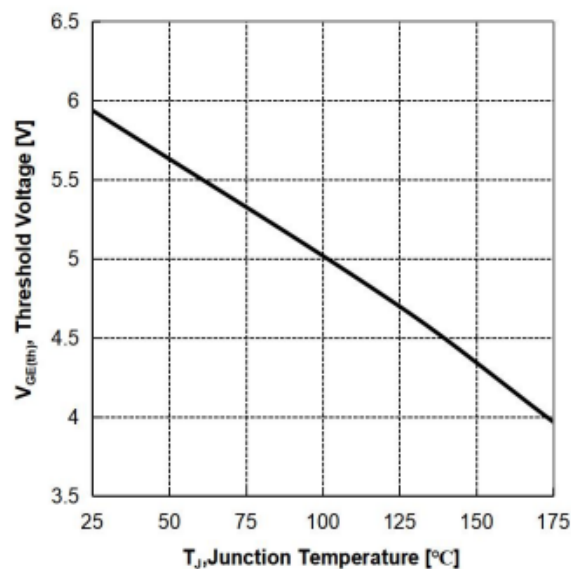
**Figure 6: Typical Output Characteristics**



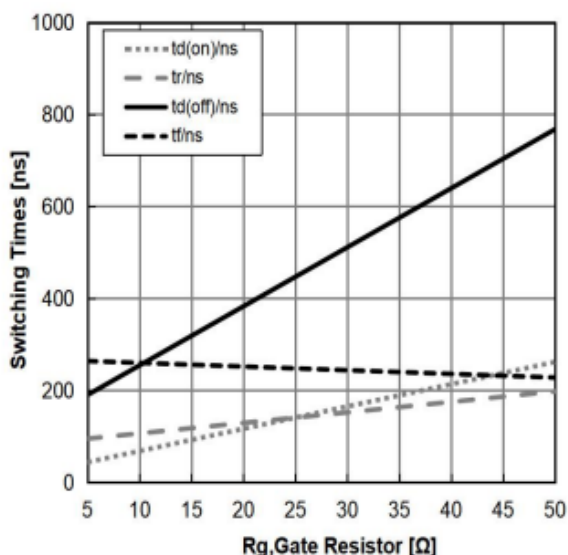
**Figure 7: Typical Collector-Emitter Saturation Voltage vs. Junction Temperature**



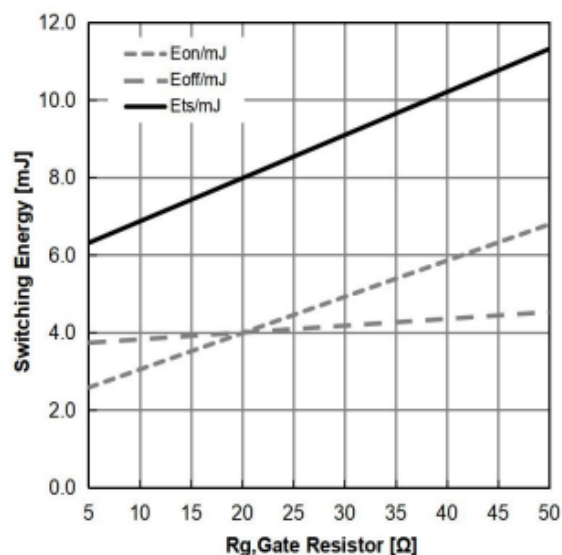
**Figure 8: Typical Gate-Emitter Threshold Voltage vs. Junction Temperature**



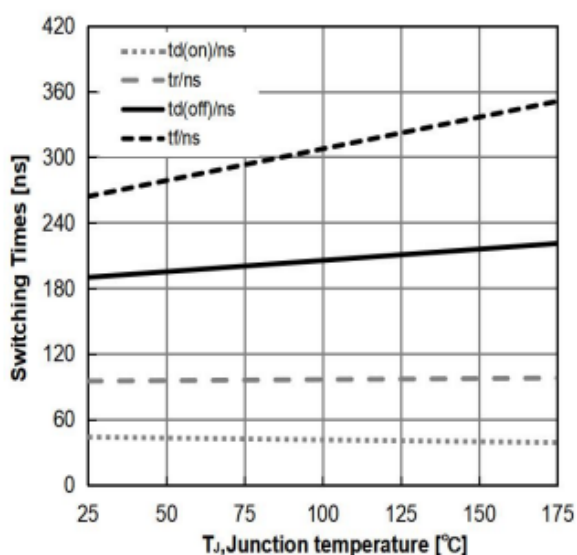
**Figure 9: Typical Switching Times vs. Gate Resistor ( $T_J=25^{\circ}\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $I_C=50\text{A}$ )**



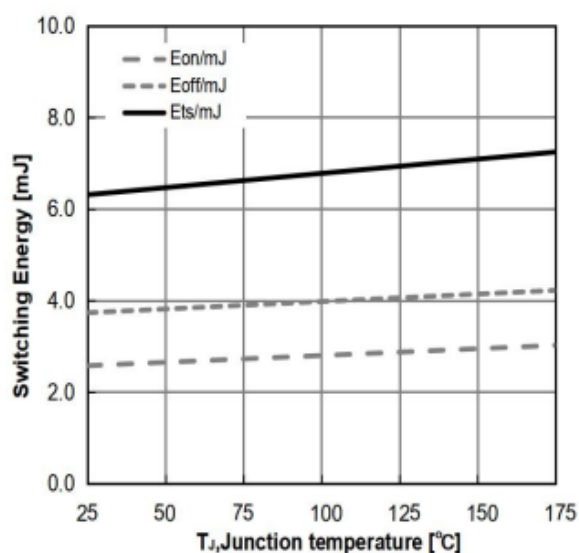
**Figure 10: Typical Switching Energy vs. Gate Resistor ( $T_J=25^{\circ}\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $I_C=50\text{A}$ )**



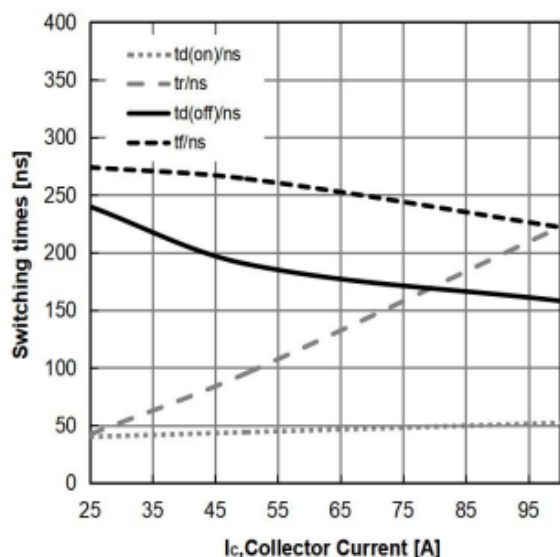
**Figure 11: Typical Switching Times vs. Junction Temperature ( $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $I_C=50\text{A}$ ,  $R_g=5\Omega$ )**



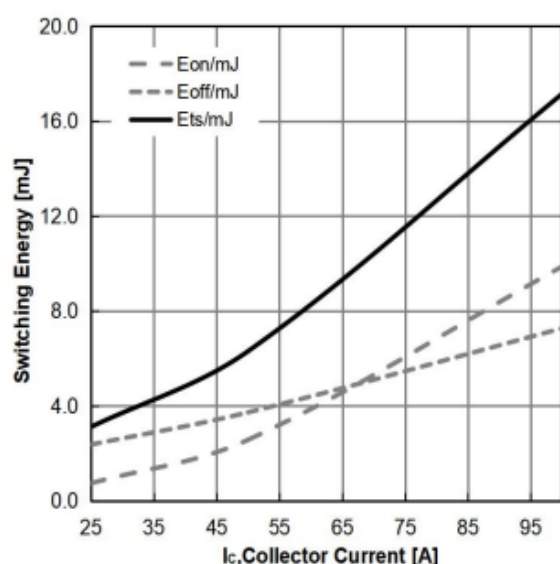
**Figure 12: Typical Switching Energy vs. Junction Temperature ( $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $I_C=50\text{A}$ ,  $R_g=5\Omega$ )**



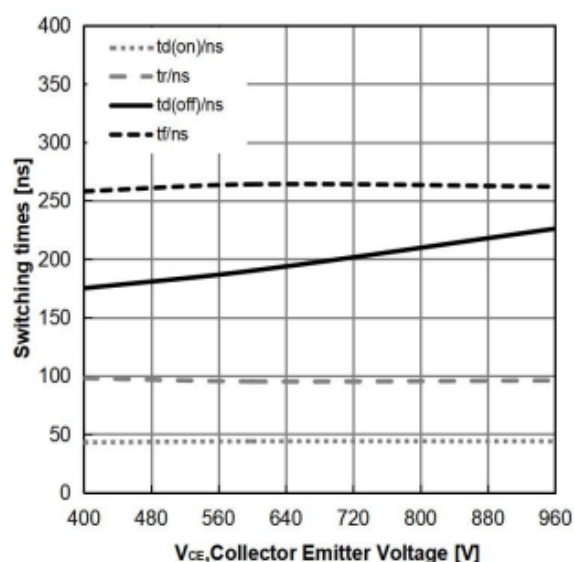
**Figure 13: Typical Switching Times vs. Collector Current ( $T_J=25^{\circ}\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $R_g=5\Omega$ )**



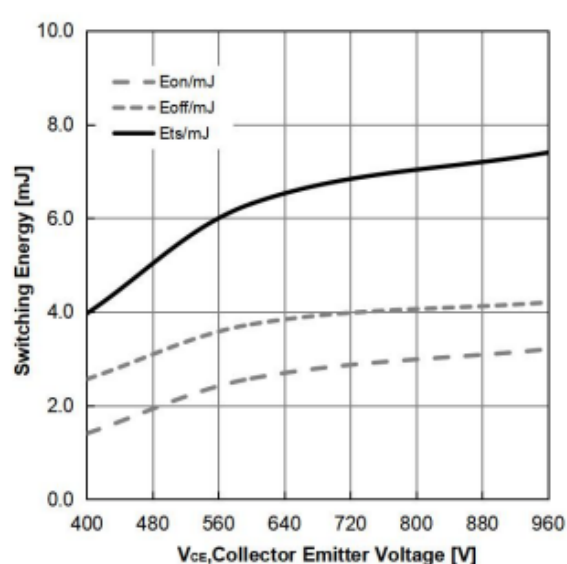
**Figure 14: Typical Switching Energy vs. Collector Current ( $T_J=25^{\circ}\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $R_g=5\Omega$ )**



**Figure 15: Typical Switching Times vs. VCE ( $T_J=25^{\circ}\text{C}$ ,  $V_{GE}=15\text{V}$ ,  $I_c=50\text{A}$ ,  $R_g=5\Omega$ )**

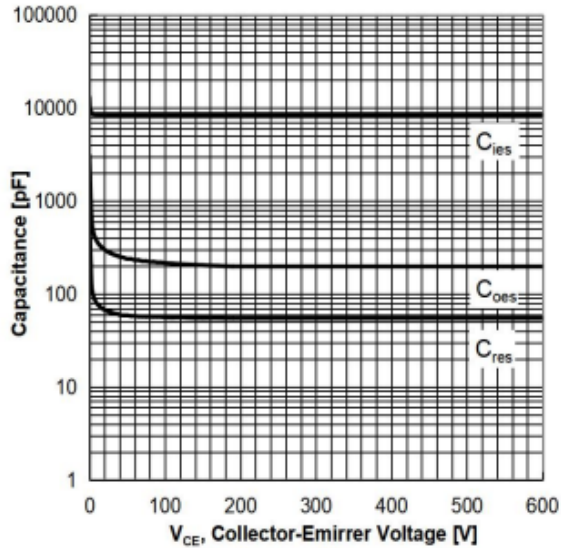


**Figure 16: Typical Switching Energy vs. VCE ( $T_J=25^{\circ}\text{C}$ ,  $V_{GE}=15\text{V}$ ,  $I_c=50\text{A}$ ,  $R_g=5\Omega$ )**

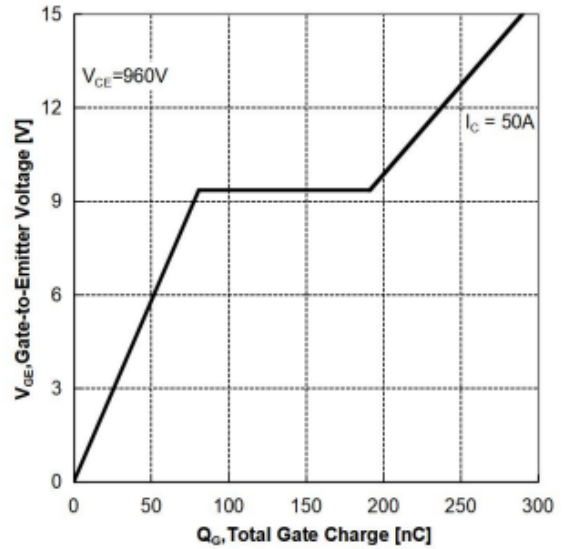




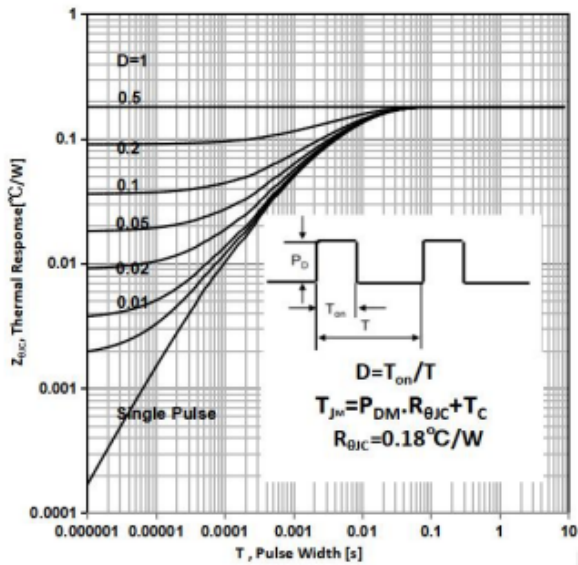
**Figure 17: Typical Capacitance vs. Collector- Emitter Voltage**



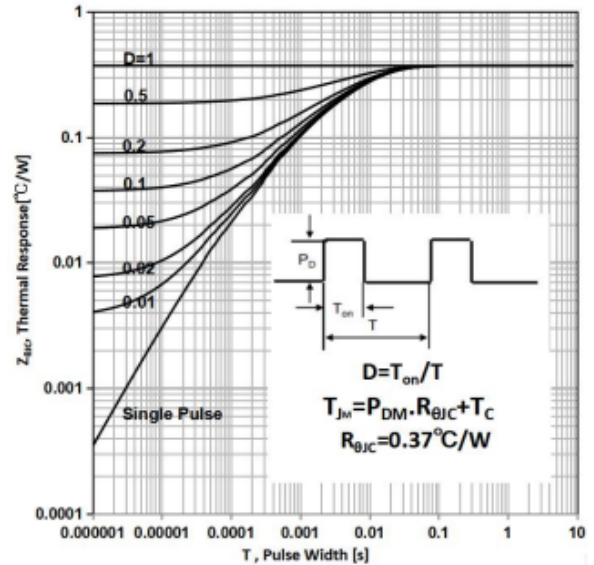
**Figure 18: Typical Gate Charge**



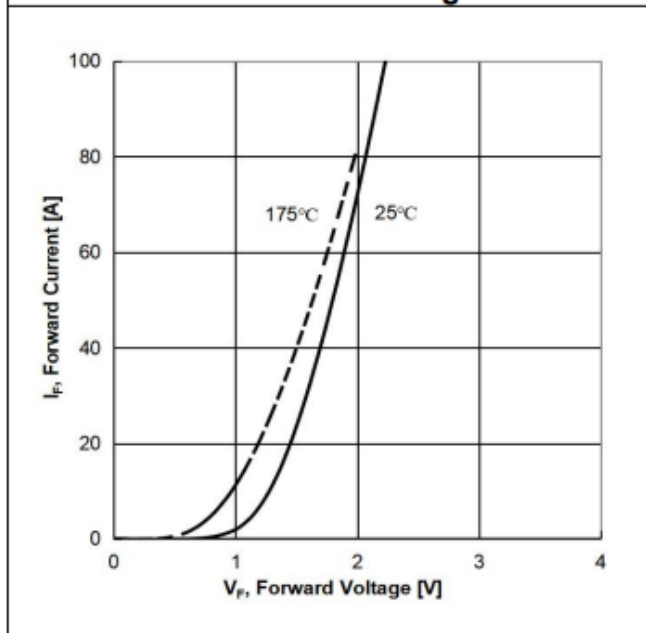
**Figure 19: IGBT Transient Thermal Impedance vs. Pulse Width**



**Figure 20: Diode Transient Thermal Impedance vs. Pulse Width**

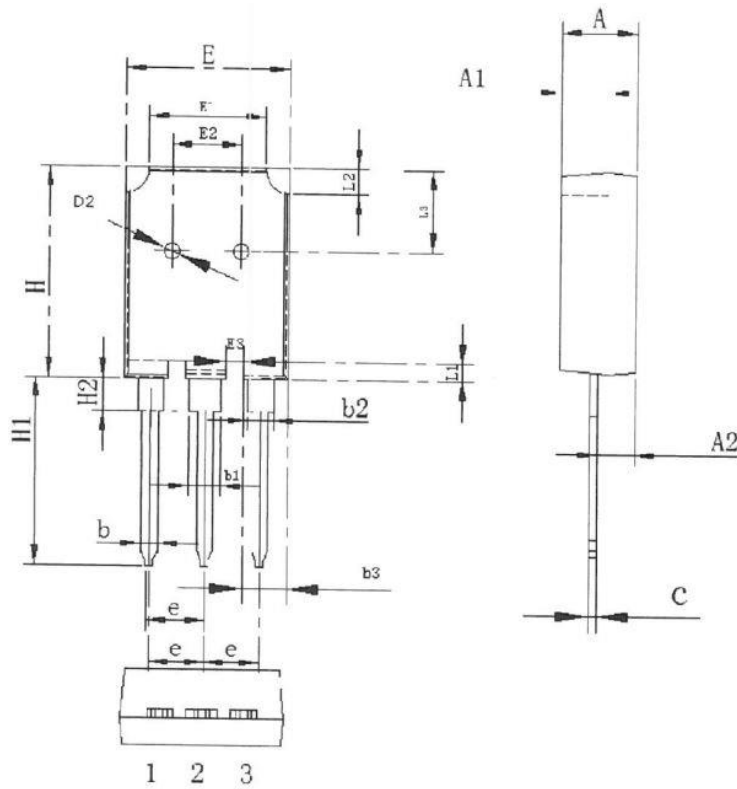


**Figure 21: Typical Diode Forward Current vs. Forward Voltage**





**TO-247Plus PACKAGE OUTLINE**



Symbol	单位 mm		
	Min	Nom	Max
A	4.80	5.00	5.20
A1	2.80	3.0	3.20
A2	1.80	2.0	2.20
b	1.00	1.20	1.40
b1	2.90	3.10	3.30
b2	1.90	2.10	2.30
b3	3.90	4.10	4.30
c	0.45	0.60	0.75
e	5.25	5.45	5.65
E	15.6	15.8	16.0
E1	10.2	10.6	11.0
E2	6.30	6.06	6.90
E3	1.60	1.80	2.00
L1	0.35	0.50	0.65
L2	1.80	2.00	2.20
L3	9.50	10.0	10.5
H	20.5	21.0	21.5
H1	19.5	20.0	20.5
H2	3.50	4.00	4.50

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